Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model **[List multiple models if applicable.]**
HPE Altoline 9960 FM1 Fabric Module (JC911A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)	AL-POLY capacitor	94
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

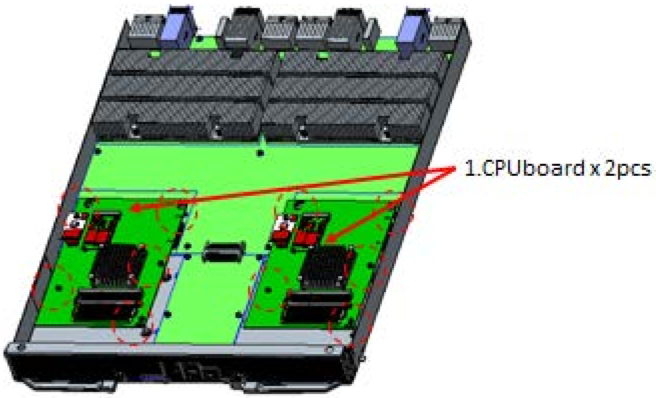
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

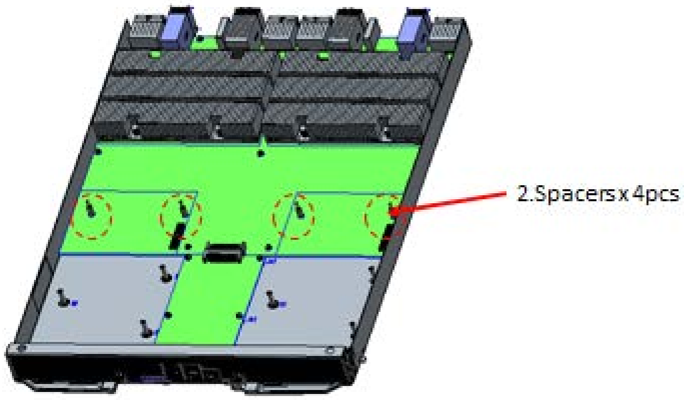
Tool Description	Tool Size (if applicable)
Phillips screwdriver	M3
Nut spinner screwdriver	5mm
Nut spinner screwdriver	5.5mm

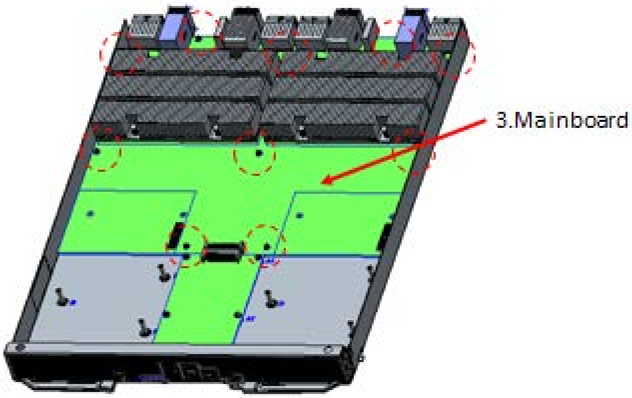
3.0 Product Disassembly Process

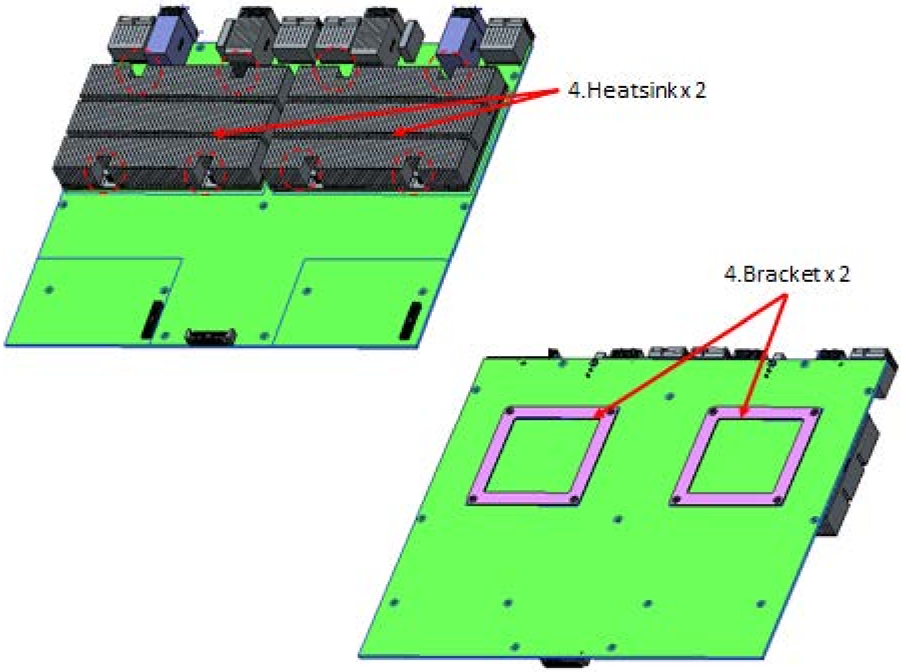
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

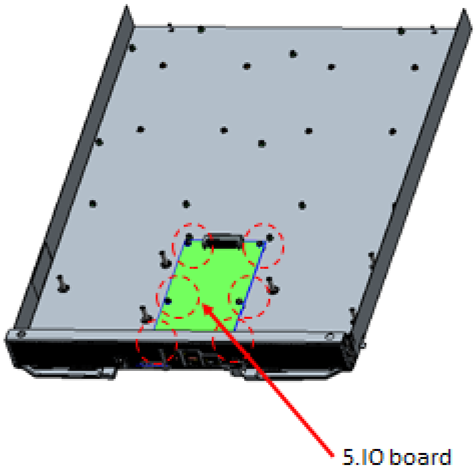
1. **Remove the CPU board**
    1. Using a 5.5mm Nut spinner screwdriver, remove the 3pcs nuts attaching the CPU board.
    2. Using a Phillips screwdriver, remove the 2pcs screws attaching the CPU board.
    3. Remove the CPU board off the chassis.
    4. Repeat for the other CPU board.
2. **Remove the spacers**
    1. Using a 5mm Nut spinner screwdriver, remove the 2pcs spacers under the CPU board.
    2. Repeat for the other 2pcs spacers.
3. **Remove the mainboard**
    1. Using a Phillips screwdriver, remove the 10pcs screws attaching the mainboard.
    2. Remove the mainboard.
4. **Remove the heatsink and bracket on the mainboard**
    1. Using a Phillips screwdriver, loose the 4pcs screws attaching the heatsink.
    2. Remove the heatsink and bracket.
5. **Remove the IO board**
    1. Using a Phillips screwdriver, remove the 6pcs screws attaching the IO board.
    2. Remove the IO board.
6. **Remove the luggage tab.**

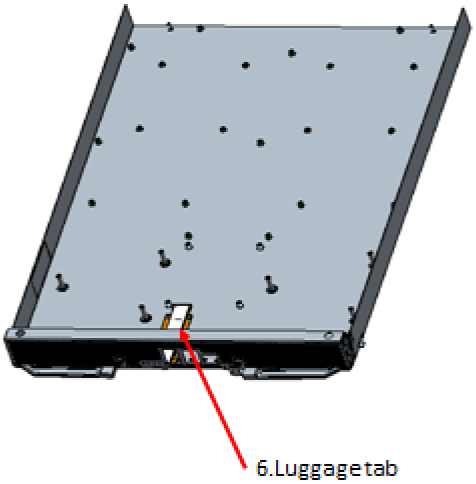

1.CPUboard x 2pcs


2.Spacers x 4pcs


3.Mainboard


4.Heatsink x 2
4.Bracket x 2


5.IO board


6.Luggage tab